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April 25, 2002

To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
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TC 1700

Subject:	Serial No. 10/083,990 02/26/02
	Zhe Wang et al.
	APPARATUS AND PROCESS FOR BULK WET ETCH WITH LEAKAGE PROTECTION
	Grp. Art Unit: 1746

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner of Patents and
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Stephen B. Ackerman, Reg.# 37761

Signature/Date

Stephen B. Ackerman 4/29/02

U.S. Patent 5,879,572 to Folsom et al., "Method of Protecting Silicon Wafers During Wet Chemical Etching," discloses a bulk wet etch method.

U.S. Patent 5,338,416 to Mlcak et al., "Electrochemical Etching Process," discloses a method of photo-assisted electrochemical machining of micromechanical structure from a silicon substrate having both p and n regions in a hydrofluoric electrolyte solution.

U.S. Patent 6,025,278 to Rolfson, "Methods for Manufacturing Semiconductive Wafers and Semiconductive Material Stencil Masks," discloses a bulk wet etch process and apparatus in which the presence of etchant on the front side of the wafer is monitored and used to terminate etching once etch-through of via holes through the wafer has been achieved.

Sincerely,



Stephen B. Ackerman,
Reg. No. 37761

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.